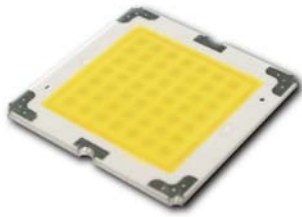


Ultra High Power LED



50W EdiStar

EdiStar Emitter

Approved By Customer	Designer	Checker	Approval

Date : 2006/12/04

Version : Preliminary V0.1

EDISON OPTO CORPORATION

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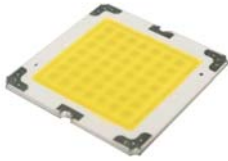
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50W EdiStar



EdiStar emitters are the brightest LEDs in the world by Edison Opto. EdiStar emitters are designed to satisfy more and more Solid-State lighting High Power LED applications for brilliant world such as general lighting, street light and projector light engine. EdiStar emitters are designed by particular package for High Power LED. 50W EdiStar white has typical 1800 lumens @2400mA. Unlike the fluorescent sources, EdiStar contains no mercury and has more energy efficient than other incandescent light source.

Features

- Outstanding thermal performance
- LED lighting engine
- Ultra high power LED

Typical Applications

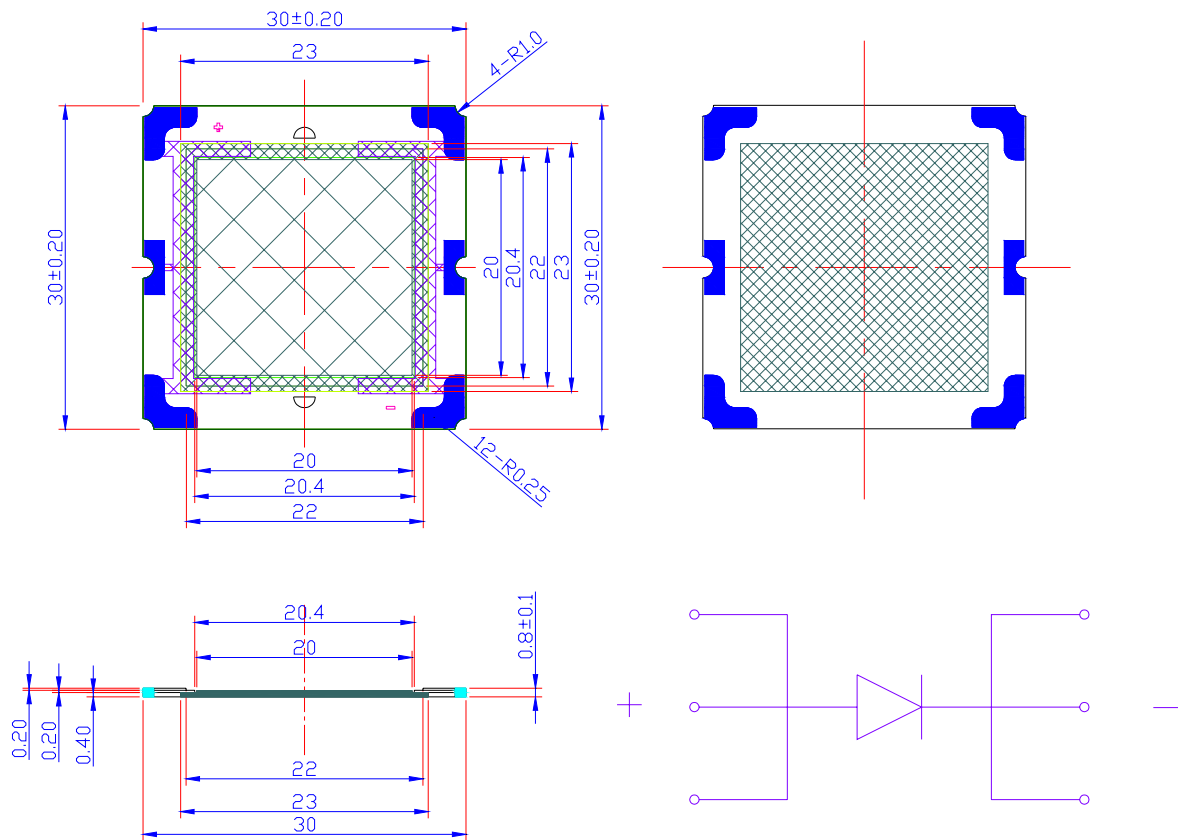
- General lighting
- Ceiling lights
- Indoor and Outdoor Commercial lighting

Technology

- $T_{jmax} = 125^{\circ}C$
- High Lumen performance
- Low thermal resistance $0.5\sim 1^{\circ}C/W$
- RoHS compliant
- Industrial best lumen maintenance —
50,000hrs life at I_{Fmax} with 70% lumen if T_j is lower than $65^{\circ}C$



Package Outlines: 50W



Notes:

1. All dimensions are in mm.
2. Drawings are not to scale.

Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
DC Forward Current	I_F	4900	mA
Peak pulse current;(tp ≤ 100μs, Duty cycle=0.25)	I_{pulse}	7000	mA
Reverse Current	I_R	50	μA
Transient Surge Voltage	V_{TS}	50	V
Isolation Voltage	V_i	1000	V
LED Junction Temperature	T_j	125	°C
LED Substrate Temperature	T_s	100	°C
Operating Temperature	T_{opr}	-30 ~ +60	°C
Storage Temperature	T_{stg}	-40 ~ +60	°C
ESD Sensitivity	V_B	500	V
Manual Soldering Time at 400°C(Max.)	T_{sol}	5	seconds

Notes:

1. Proper current derating must be observed to maintain junction temperature below the maximum.
2. LEDs are not designed to be driven in reserve bias.

Luminous Flux & Electrical Characteristics (T_j=25°C):

Power Consumption	Part Name	Color	Typ. Voltage (V)	Current (A)	Luminous Flux (lm)	Thermal Resistance (°C/W)
50W	ENEW-05-0707-DA	White	23	2.4	1800	0.5
	ENEX-05-0707-DC	Warm White	23	2.4	1400	0.5

Luminous Flux Characteristics at I_F=2400mA (T_j=25°C):

Power Consumption	Part Name	Color	Flux			Units
			Min.	Typ.	Max.	
50W	ENEW-05-0707-DA	White	1600	1800	--	<i>lm</i>
	ENEX-05-0707-DC	Warm White	1250	1400	--	<i>lm</i>

Color Temperature Characteristics at I_F=2400mA (T_j=25°C):

Power Consumption	Part Name	Color	λ _d /λ _p ⁽¹⁾ /CCT			Units
			Min.	Typ.	Max.	
50W	ENEW-05-0707-DA	White	4000	--	8000	<i>K</i>
	ENEX-05-0707-DC	Warm White	2800	--	3800	<i>K</i>

Emission Angle Characteristics at I_F=2400mA (T_j=25°C):

Part Name	Color	2θ _{1/2} (Typ.)	Units
ENEW-05-0707-DA	White	140	Degrees
ENEX-05-0707-DC	Warm White	140	Degrees

Note

1. Flux is measured with an accuracy of ± 10%.
2. CCT selection acc. To CCT groups and an accuracy of ± 300K
3. Forward Voltage is measured with an accuracy of ± 0.1V
- 3 All white and warm white emitters are built with InGaN

Operating life and environmental tests performed on EdiStar™ package:

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature Operating Life	25°C, I _F = max DC (Note 1)	1000 hours	Note 2
High Temperature High Humidity	85°C / 85%RH	1000 hours	Note 2
Temperature Cycle	-40°C/100°C ,30 min dwell / <5min transfer	200 cycles	Note 2
High Temperature Storage Life	110°C	1000 hours	Note 2
Low Temperature Storage Life	-55°C	1000 hours	Note 2
Thermal Shock	-40 / 120°C, 20 min dwell / <20 sec transfer	200 cycles	No catastrophics

Note

1. Depending on the maximum derating curve.

2. Failure Criteria:

Electrical failures

V_F shift >=10%

I_R<50uA @V_r=5V

Light Output Degradation

% Iv shift >= 20% @1,000hrs or 200cycle

Visual failures

Broken or damaged package or lead

Solderability < 95% wetting

Dimension out of tolerance

How to Know Tj in Your Application?

If it is white EdiStar™ Rth(junction to case)=0.5°C/W

The thermal grease is 200um.

K(thermal conductivity)=3 W/mk

$$\text{Then Rth(case to board)} = \frac{200}{3 \times (18)^2} = 0.2 \text{ } ^\circ\text{C/W}$$

The Rth between board and air is mainly dependent on the total surface air.

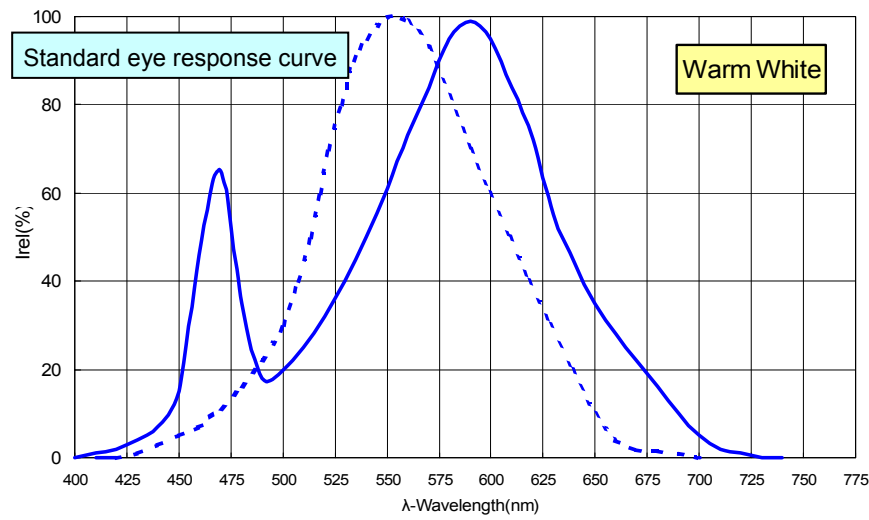
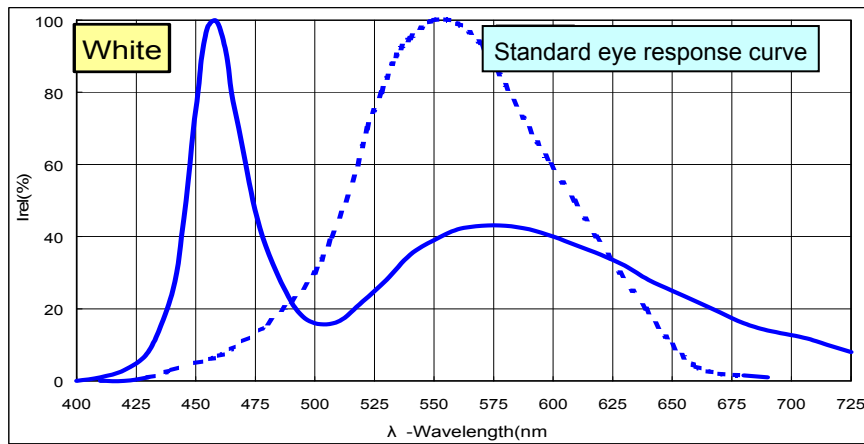
$$\text{Rth(board-air)} \doteq \frac{500}{\text{Area(cm}^2\text{)}}$$

If Area is 3000cm² Rth=0.167 $\Delta T(\text{junction-air})=(0.5+0.2+0.167) \times 50=43.35 \text{ } ^\circ\text{C}$

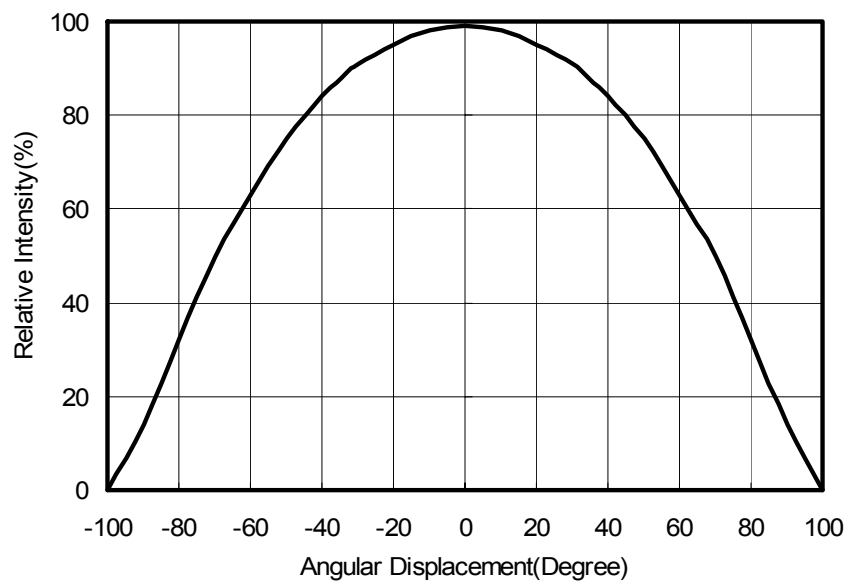
If Area is 5000cm² Rth=0.1 $\Delta T(\text{junction-air})=(0.5+0.2+0.1) \times 50=40 \text{ } ^\circ\text{C}$

If Area is 8000cm² Rth=0.0625 $\Delta T(\text{junction-air})=(0.5+0.2+0.0625) \times 50=38.125 \text{ } ^\circ\text{C}$

Electrical & Optical Curves-Spectrum



Typical Radiation Pattern for white and warm white



Adhesive for Emitter to Aluminum PCB

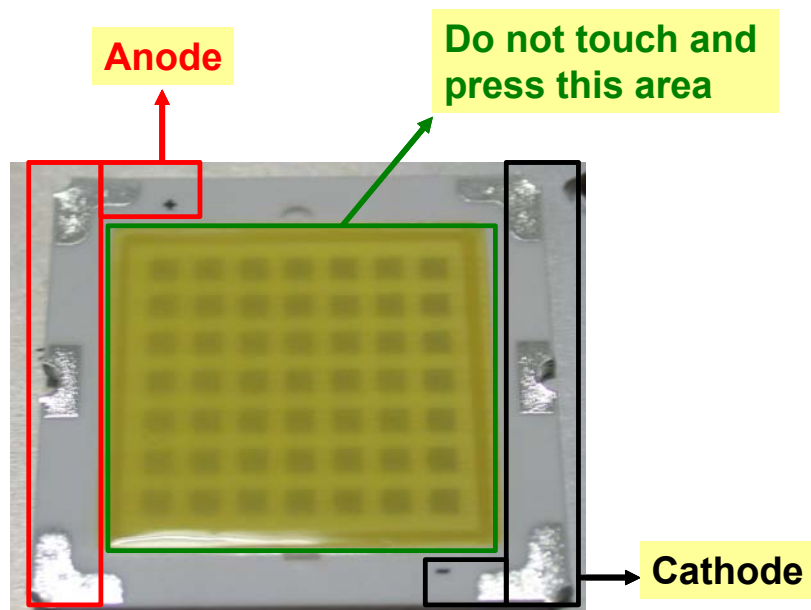
Suggestion:

- Ease of use
 - Non-solvent, One-part
- Fast tack free
 - 3 minutes at 25°C
- No corrosion
 - Alcohol type of RTV
- Low volatility
 - Low weight loss of silicone volatiles
- Adhesion
 - Excellent adhesion to most materials without use of a primer
- Dielectric properties
 - Cured rubber exhibits good dielectric properties
- Excellent thermal stability and cold resistance
 - Cured rubber provides wide service temperature range

Typical Properties

Specification	Suggested Properties
Thermal grease	Silicone base
Take-free time	3~10 minutes
Specific gravity	< 3 g/cm ²
Thermal conductivity	> 3.5 W/mK
Rth in using	< 1 °C/W
Volume resistance	> 1x10 ⁶ MΩm
Lap shear adhesion strength	> 200 N/ cm ²
Tensile strength	> 4 Mpa
Bond Line Thickness	<40um

Instruction for Proper Usage:



Driver:

- Input Constant Current=2.1~2.4A
- Input Voltage (min) =24V

Assembly Steps:

1. Spread thermal grease on heat sink or the bottom of EdiStar uniformly.
2. Place EdiStar on heat sink and press it lightly.
3. The heat sink should be anodized.
4. Wire up EdiStar and connect to driver.
5. Use constant current driver.

Thermal grease:

GE TIG825FX or thermal conductivity is greater than 4 w/mk.

The thickness of thermal grease between LED and heat sink should be less than 200 μm

Surface area of heat sink:

Larger than 5000 cm^2 (suggestion)